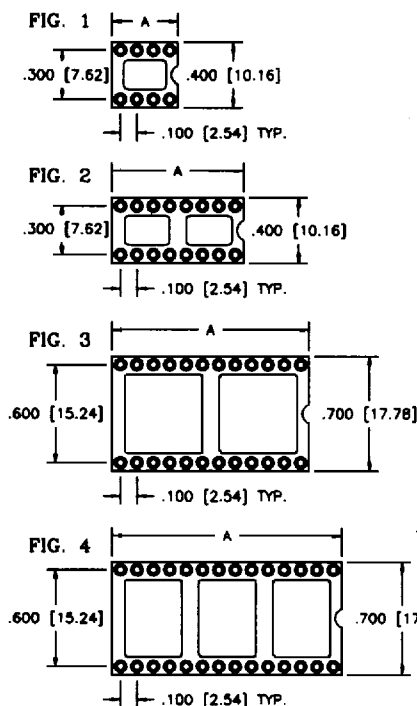
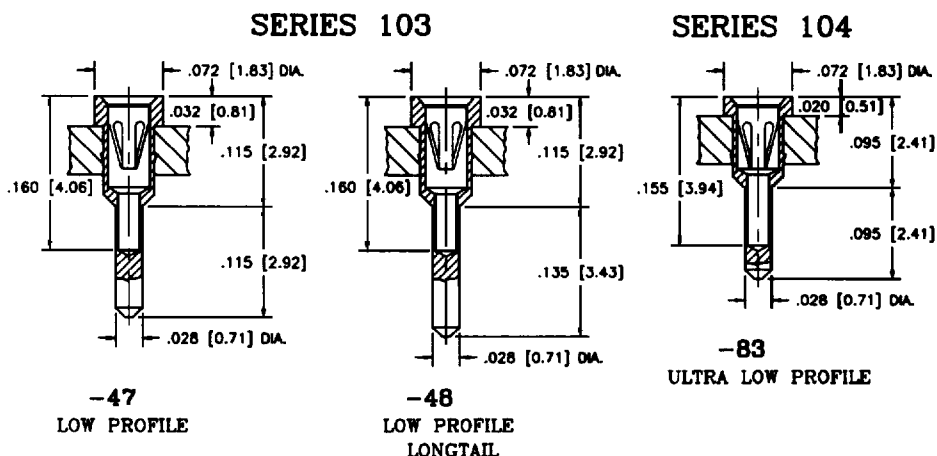


SERIES 103 LOW PROFILE DIP SOCKET (OPEN FRAME)

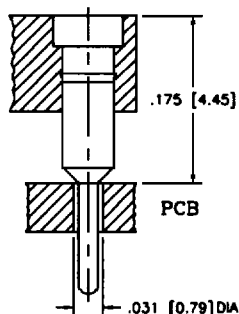
SERIES 104 ULTRA LOW PROFILE DIP SOCKET (OPEN FRAME)

SERIES 105 ULTRA LOW PROFILE DIP SOCKET (OPEN FRAME WITHOUT CROSSBARS)

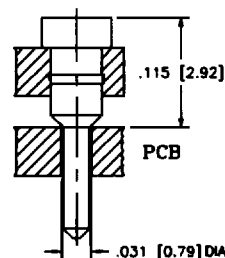
WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
	28	1.400 [35.56]	328
	32	1.600 [40.64]	332
FIG. 3	24	1.200 [30.48]	624
	28	1.400 [35.56]	628
FIG. 4	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640



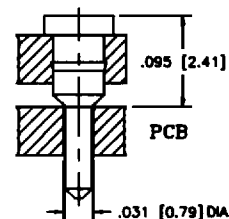
STANDARD HEIGHT
ABOVE PCB
WITH -01 TERMINAL



34%
REDUCED HEIGHT
WITH -47 TERMINAL



46%
REDUCED HEIGHT
WITH -83 TERMINAL



CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR	GLASS FILLED POLYESTER
	UL 94V-0 LISTED
TERMINAL CONTACT	BRASS PER ASTM-B16
	BeCu PER ASTM-B194
OPERATING TEMP.	-65°C TO +125°C
CONTACT FORCES	
INSERTION	STANDARD 9 oz. AVG.
WITHDRAWAL	STANDARD 2 oz. MIN.

ORDERING INFORMATION

10X-XXX-XXX-PXX-B10		NO LOGO
SERIES	103: LOW PROFILE	INSULATOR MATERIAL
	104: ULTRA LOW PROFILE	OTHER MATERIALS AVAILABLE
	105: WITHOUT CROSSBARS	CONSULT FACTORY
DIP - SPACING		PLATING: TERMINAL / CONTACT
NO. OF PINS		P30: GOLD / GOLD
TERMINAL STYLE		P31: TIN-LEAD / GOLD
FOR OPTIONAL TERMINAL STYLES		P32: TIN-LEAD / TIN
SEE TERMINAL STYLES		OTHER PLATINGS AVAILABLE
CONTACT TYPE		SEE OPTIONAL PLATINGS